

ABSTRACT OF THE DISCLOSURE

SHEET FOR SEALING HOLLOW ELECTRONIC DEVICE AND METHOD FOR PRODUCING HOLLOW ELECTRONIC DEVICE PACKAGE

It is an object of the present invention to provide a sheet for sealing a hollow electronic device which can suppress variation for every package in the amount of a resin entering into a hollow part between an electronic device and an adherend. A sheet for sealing a hollow electronic device, wherein: loss tangent $\tan \delta$ at 50 to 90°C is 0.3 or more and 0.8 or less; a storage modulus at 50 to 90°C is 1.0×10^5 or less; loss tangent $\tan \delta$ at 150°C is 0.35 or less; and a storage modulus at 150°C is 1.0×10^6 or less.

FIG. 1